

# Alfredo Perez, Jr.

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## OBJECTIVE

An internship with an engineering group working in a technical field, preferably design, communications, or signal processing

## EDUCATION

<b>Master of Science in Electrical Engineering</b> The University of Texas at El Paso (UTEP)	GPA: 3.4/4.0	December 2004
<b>Bachelor of Science in Electrical Engineering</b> The University of Texas at El Paso	GPA: 3.59/4.0	December 2002

**Relevant Coursework:** VLSI Design, RFIC Design, Digital Signal Processing, Digital Communications, Random Processes, Digital Image Processing, RT Signal Processing using the TMS320C6711 DSK

## EXPERIENCE

<b><u>Wireless Communications</u></b>	UTEP – Graduate Research	12.03 – Current
<ul style="list-style-type: none"><li>Working in the design of a multi-standard (GSM/WCDMA) direct-conversion receiver IC using Agilent's ADS tools</li><li>Currently focused on designing the front-end low noise amplifier (LNA)</li></ul>		
<b><u>Teaching Assistant</u></b>	UTEP – Electrical Engineering Department	01.03 – 12.03
<ul style="list-style-type: none"><li>Lab coordinator for Senior Project Design I course</li><li>Supervisor, facilitator and grader for 11 teams working on various engineering projects</li></ul>		
<b><u>Acoustic Signal Processing</u></b>	UTEP – Senior Projects	01.02 – 12.02
<ul style="list-style-type: none"><li>Translated an infrasonic signal processing algorithm developed by the Army Research Labs from MATLAB to C</li><li>Implemented filtering, windowing, FFT and other signal processing routines on a TMS320C6701 TI EVM board</li></ul>		
<b><u>Test &amp; Product Development</u></b>	Texas Instruments, Inc – BCG WLAN	05.02 - 08.02, 05.01 - 08.01
<ul style="list-style-type: none"><li>Supported Monitored Burn In (MBI) solution for ACX100B WLAN processor in MAX3 oven</li><li>Performed TDL conversion processes and BIB checkout procedures for MAX3 and AEHR12000 BI</li><li>Studied implementation of latch-up testing on the ATE environment</li><li>Handled ESD qualification (Human Body and Charged Device Models) process for WLAN products</li></ul>		
<b><u>Product Engineering</u></b>	Texas Instruments, Inc – SBU SPARC	05.00 - 08.00, 05.99 - 12.99
<ul style="list-style-type: none"><li>Supported product reliability evaluations and analysis of data of Sapphire Black and Blaze microprocessors</li><li>Processed and verified electrical reads of customer returns and engineering samples on the ATE environment</li><li>Performed characterization studies for process flow qualifications (burn-in) and contact resistance</li></ul>		
<b><u>Product Marketing</u></b>	Texas Instruments, Inc – DSP Product Marketing	05.99 - 08.99
<ul style="list-style-type: none"><li>Communicated and interacted with technical sales representatives to perform customer end-equipment analysis</li><li>Collected and organized surveying data for TMS320C5x DSP family roadmap planning and for C5000 Code Composer Studio tools beta program</li></ul>		

## ACTIVITIES

Institute of Electrical and Electronics Engineers	IEEE	President	02-03
Engineering Student Leadership Council	ESLC	External Relations Chair	01-02
Society of Mexican American Engineers and Scientists	MAES	Secretary	00-01
Society of Hispanic and Professional Engineers	SHPE	Secretary	00-01

## HONORS AND AWARDS

UTEP Bridge to the Doctorate Research Fellowship	LSAMP		F03 – SP05
Eta Kappa Nu – Electrical Engineering Honor Society	HKN	Secretary	02-03
Alpha Phi Omega Outstanding Engineering Student	APO		SP02
Hispanic Scholarship Fund Scholarship			2002
MAES General Scholarship			01-02

## SKILLS

**SOFTWARE:** Classroom experience using C, MATLAB, Perl, TI Code Composer Studio, Agilent ADS, Microsoft Office

**PEOPLE:** Team player, good organizational skills, fine presenter, bilingual in both English and Spanish

**OTHER:** Proficient soccer player, amateur guitar player